


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	DESIGN OF BEOL PATTERNS TO REDUCE THE STRESSES ON STRUCTURES BELOW CHIP BONDPADS		
Application Type : regular, utility Attorney Docket Number : BUR920030175US1			
Correspondence address: Customer Number: 29154 			
Inventors Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: US Given Name: Elie Family Name: Awad Residence: City of Residence: Essex Junction State of Residence: VT Country of Residence: US Address-1 of Mailing Address: 38 Thasha Lane, #D4 Address-2 of Mailing Address: City of Mailing Address: Essex Junction State of Mailing Address: VT Postal Code of Mailing Address: 05452 Country of Mailing Address: US Phone: Fax: E-mail: <u>Inventor 2:</u> Applicant Authority Type: Inventor Citizenship: US Given Name: Mariette Middle Name: A. Family Name: Awad			

Residence:

City of Residence: Essex Junction
State of Residence: VT
Country of Residence: US
Address-1 of Mailing Address: 38 Thasha Lane, #D4
Address-2 of Mailing Address:
City of Mailing Address: Essex Junction
State of Mailing Address: VT
Postal Code of Mailing Address: 05452
Country of Mailing Address: US
Phone:
Fax:
E-mail:

Inventor 3:

Applicant Authority Type: Inventor
Citizenship: CA
Given Name: Kai
Middle Name: D.
Family Name: Feng
Residence:
City of Residence: Essex Junction
State of Residence: VT
Country of Residence: US
Address-1 of Mailing Address: 30 Fairview Drive
Address-2 of Mailing Address:
City of Mailing Address: Essex Junction
State of Mailing Address: VT
Postal Code of Mailing Address: 05452
Country of Mailing Address: US
Phone:
Fax:
E-mail:

Assignee 1:

Organization Name: International Business Machines Corporation
Address-1 of Mailing Address: New Orchard Road
Address-2 of Mailing Address:
City of Mailing Address: Armonk
State of Mailing Address: NY
Postal Code of Mailing Address: 10504

Country of Mailing Address:

US

Phone:

Fax:

E-mail: